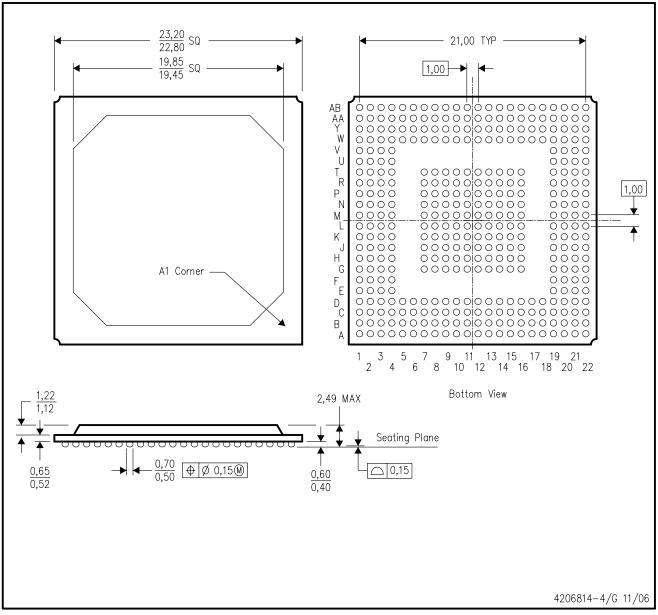
ZDW (S-PBGA-N388)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-151
- D. Thermally enhanced plastic package
- E. This package is a lead free solder ball design.



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